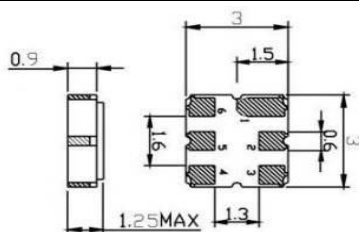


Specification Sheet

Customer Name	XXXX	CUST P/N	NA
Approval No.	PD	Temwell P/N	STSF-2150B40-S3030W
Lot No.		Date	2025.06.24
Description	SAW Filter (BandPass)	Version	A1

(1)Size Diagram (Unit : MM)



PinNo.	Description
2	Input
5	Output
1,3,4,6	Ground
Tolerance	±0.1mm

(2)Electrical Specifications

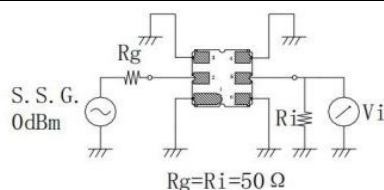
Item			Specification		
Parameter	MHz	Unit	Min.	Typical	Max.
Center Frequency	-	MHz	-	2150	-
Insertion Loss	2150	dB	-	2.0	2.5
Insertion Loss	2130-2170	dB	-	2.8	3.5
Ripple	2130-2170	dB	-	0.8	1.0
Group Delay	2130-2170	ns	-	10	30
Attenuation	DC-850	dB	35	40	-
	850-1710	dB	35	40	-
	1710-1785	dB	38	45	-
	1785-1940	dB	43	45	-
	1940-1980	dB	43	45	-
	2300-2400	dB	45	50	-
VSWR	2400-3600	dB	30	35	-
	2130-2170	dB	-	1.6:1	2.0:1
Operation Temperature	-40°C~+85°C	°C	-	-	-
Storage Temperature	-40°C~+125°C	°C	-	-	-
RF Power Dissipation	20	dBm	-	-	-

Remark

Note 1: Test Temperature: 25°C±2°C

Note 2: Terminating source impedance: 50Ω. Terminating load impedance: 50Ω

(3)Test Circuit



$$R_g = R_i = 50 \Omega$$

Port	Matching component
Input	R1: 50Ω
Output	R2: 50Ω

Figure 1. Electrical Characteristics: Frequency response

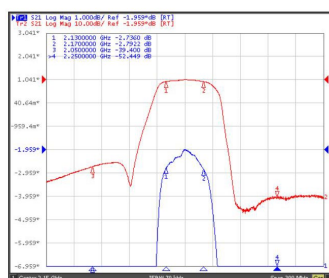
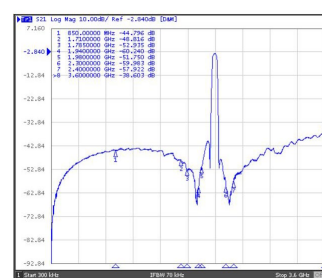
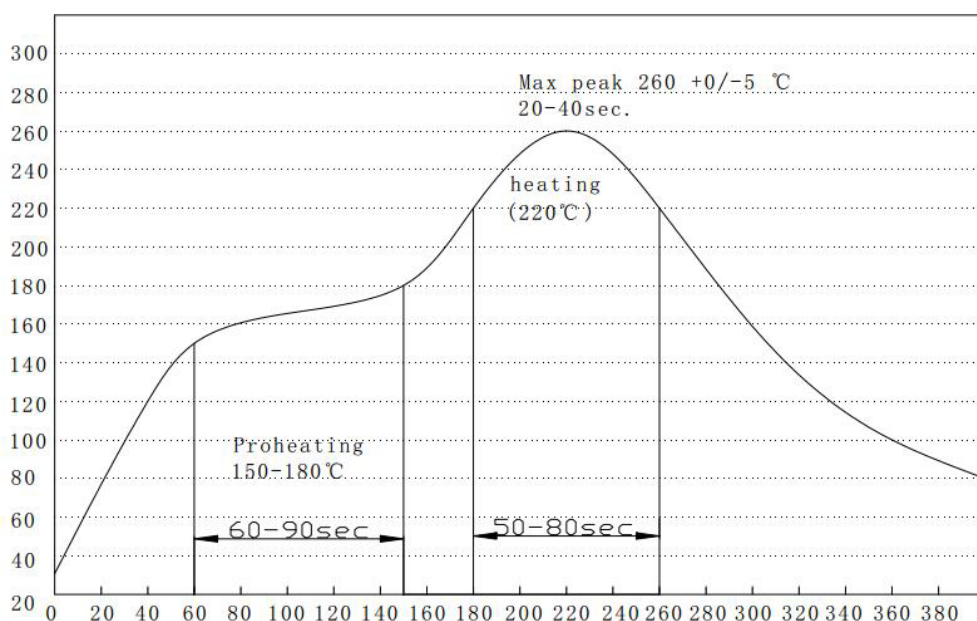


Figure 2. Electrical Characteristics: Wideband



Approval	Supervisor	Designer
C. K. Chang	M. Y. Chen	F.L.Lai

Recommended SMT Solder Profile



Reliability

No.	Test item	Test condition	
1	Temperature Storage	Temperature: 85°C±2°C , Duration: 250h , Recovery time: 2h±0.5h Temperature: -40°C±3°C , Duration: 250h ,Recovery time: 2h±0.5h	
2	Humidity Test	Conditions: 60°C±2°C ,90~95%RH	Duration:250h
3	Thermal Shock	Heat cycle conditions: TA=-40°C±3°C, TB=85°C±2°C, t1=t2=30min, Switch time: ≤3min, Cycle time: 100 times, Recovery time: 2h±0.5h.	
4	Vibration Fatigue	Frequency of vibration:10~55Hz Directions: X,Y and Z	Amplitude:1.5mm Duration: 2h
5	Drop Test	Cycle time:10times	Height:1.0m
6	Solder Ability Test	Temperature:245°C±5°C Depth: DIP--2/3, SMD--1/5	Duration:3.0s--5.0s
7	Resistance to Soldering Heat	Thickness of PCB:1mm , Solder condition: 260°C±5°C , Duration:10±1s Temperature of Soldering Iron: 350°C±10°C, Duration: 3~4s, Recovery time : 2 ± 0.5h	